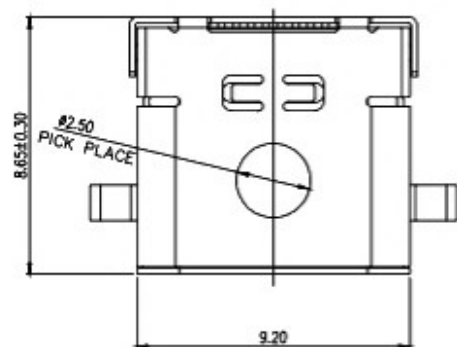


NOTES:1.MATERIAL:

MOLDING: LCP UL94 V-0

CONTACT: COPPER ALLOY.

GOLD PLATED Min ON CONTACT AREA, 100u"

Min TIN (LEAD FREE) ON SOLDER AREA,

SHELL: SUS304-H, T=0.30±0.03mm

50u" NICKEL PLATING OVER ALL.

SHILD: SUS304-H, T=0.12±0.03mm

2.MECHANICAL:

INSERTION: 5~20N.

EXTRACTION: 8~20N.

DURABILITY: 10000 CYCLES

3.ELECTRICAL:

CURRENT: 5A MIN FOR VBUS;

0.25A MIN FOR OTHER.

VOLTAGE: 20 V MAX

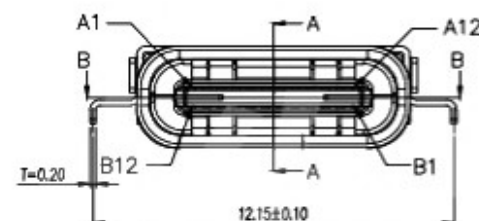
WITHSTANDING VOLTAGE: 100V AC.

CONTACT RESISTANCE: 40mΩ MAX.

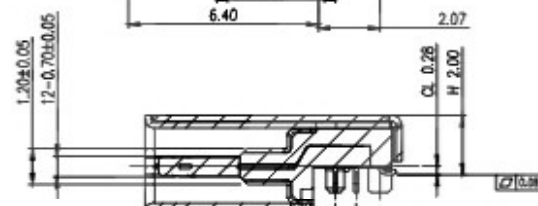
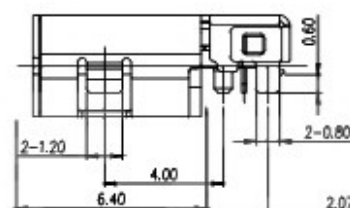
INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL

TEMPERATURE RANGE -55°C ~ +85°C



SECTION B-B



SECTION A-A

PIN NO:
04-24

MOSC - 24 7

X -

XX

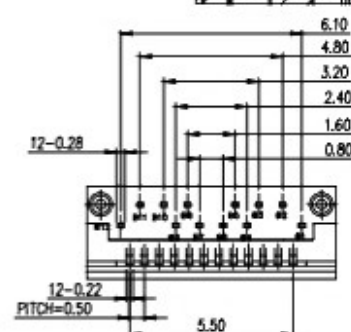
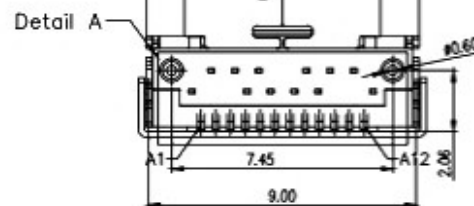
X

X

包装:
R.TAPE&REEL(卷)颜色:
B: BLCK
W: WHITE

Series No.: 09/10

K: GOLD FLASH PLATING ON CONTACT AREA
Matte Tin PLATING ON SOLDER AREA
M: 5u" GOLD PLATING ON CONTACT AREA
Matte Tin PLATING ON SOLDER AREA
P: 15u" GOLD PLATING ON CONTACT AREA
Matte Tin PLATING ON SOLDER AREA
U: 30u" GOLD PLATING ON CONTACT AREA
Matte Tin PLATING ON SOLDER AREA



Detail A



东莞市溪榜电子有限公司

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PART NAME		CONNECTOR			DRAWING	Y,C,ZHANG	DWG.No.	SBICL
PART NO.		3.1 TYPE C沉板DIP+SMT 10.0L(8.65L) 双外壳			CHECK	G.C.Chen	REV.	A1
	UNIT :	TOLERANCE OTHERWISE	UP TO 5	±0.2	APPROVAL	SCALE	DATE	PAGE
	mm		ABOVE 5 ~30	±0.3				
			ABOVE 30	±0.5		2:1		1 OF 1
			ANGLE	±3				